## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the present application.

## Listing of Claims:

Claim 1 (currently amended): A ceramic susceptor formed as a laminate having a frontside for retaining an object being processed and a backside, the laminate composed of a plurality of ceramic sheets whose sides other than the laminate trontside and backside define susceptor internal surfaces, the susceptor laminate comprising:

a resistive-heating-element circuit formed on one surface selected from said susceptor backside and said susceptor internal surfaces; and

a lead circuit for supplying electricity electric power to the resistive heating element, formed on one surface, selected from said susceptor backside and said susceptor internal surfaces, that is different from the surface on which said resistive heating element is formed; and

electrodes for supplying electric power from outside the susceptor, said electrodes connected to said lead circuit and formed inside the area in which the resistive heating element is formed.

Claim 2 (original): A susceptor as set forth in claim 1, wherein said resistiveheating-element circuit is patterned in approximately concentric circular forms.

Claim 3 (previously presented): A susceptor as set forth in claim 1, wherein the form in which said lead circuit supplies electricity to said resistive-heating-element circuit is non-planar.

Claim 4 (original): A susceptor as set forth in claim 1, wherein said resistiveheating-element circuit is patterned in a plurality of discrete zones.

Claim 5 (original): A susceptor as set forth in claim 1, wherein the temperature uniformity in said side for retaining an object being processed is within ±1.0%.

Claim 6 (original): A susceptor as set forth in claim 1, wherein the resistance of said lead circuit is smaller than the resistance of said resistive-heating-element circuit.

Claim 7 (currently amended): A susceptor as set forth in claim 1, further comprising wherein electrodes for supplying electric power from outside the susceptor, said electrodes are formed proximate to roughly the center of the ceramic susceptor and connected to said lead circuit.

Claim 8 (original): A susceptor as set forth in claim 1, wherein the susceptor thickness is 5 mm or more.

Claim 9 (original): A susceptor as set forth in claim 1, wherein the chief component of the susceptor ceramic is one selected from aluminum oxide, silicon nitride and aluminum nitride.

Claim 10 (original): A susceptor as set forth in claim 9, wherein the chief component of said ceramic is aluminum nitride.

Claim 11 (original): A susceptor as set forth in claim 10, wherein an yttrium compound is added as a sintering aid into the ceramic.

Claim 12 (original): A susceptor as set forth in claim 11, wherein the amount of the yttrium compound added is 0.01 weight % or more, and 5.0 weight % or less, in yttrium oxide  $(Y_2O_3)$  equivalent.

Claim 13 (original): A semiconductor manufacturing apparatus in which the ceramic susceptor recited in claim 1 is installed.

Claim 14 (original): A liquid-crystal manufacturing apparatus in which the ceramic susceptor recited in claim 1 is installed.

Claim 15 (currently amended): A ceramic susceptor formed as laminate having a frontside for retaining an object being processed and a backside, the laminate composed of a plurality of sheets whose sides other than the laminate frontside and backside define susceptor internal surfaces, the susceptor laminate comprising:

a resistive-heating-element circuit formed on one surface selected from said susceptor backside and said susceptor internal surfaces;

a lead circuit <u>for supplying electric power to the resistive heating element.</u>

formed on one surface, selected from said susceptor backside and said susceptor internal surfaces, that is different from the surface on which said resistive heating element is formed;

electrodes for supplying electric power from outside the susceptor, said electrodes connected to said lead circuit and formed inside the area in which the resistive heating element is formed; and

an electrical junction between said resistive-heating-element circuit and said lead circuit, said electrical junction together with said resistive-heating-element circuit and said lead circuit forming a three-dimensional conformation.